

**Amendments to the Claims:**

Cancel claims 18 through 23.

Claim 1 has been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

1. (Currently Amended) A semiconductor device having a portion thereof formed from a wafer of semiconductive material by a laser etching process comprising:  
a substrate of semiconductive wafer material having a surface;  
a semiconductor device having a portion thereof attached to a portion of the substrate;  
an interposer connected to the substrate, the interposer having a laser roughened surface ~~formed by a laser~~ increasing the surface area thereof to adhere mold material thereto in a molding operation;  
and  
a portion of resist, contamination and oxidation on at least a portion of the surface of the substrate of semiconductive wafer material having a portion thereof removed by laser etching of the resist, contamination, and oxidation from the surface of the substrate using a laser forming a portion of an automolding system prior to the encapsulation of a portion of the semiconductor device in the automolding system.

2. (Canceled)

3. (Previously Presented) The semiconductor device according to claim 1, wherein the laser includes one of an Nd:YAG laser and an excimer laser.

4. (Previously Presented) The semiconductor device according to claim 1, wherein the substrate comprises a ball-grid-array substrate.

5. (Previously Presented) The semiconductor device according to claim 1, further comprising a vision system for detecting the resist.

6. (Previously Presented) The semiconductor device according to claim 5, wherein the vision system comprises:  
a laser scanning system for detecting changes in a pattern of the substrate.

Claims 7 - 11 (Canceled)

12. (Withdrawn) A semiconductor device having a portion formed by a laser etching process on a substrate of semiconductive material having a surface comprising:  
resist located on at least a portion of the surface having a portion thereof removed by etching the resist from the at least a portion of the surface of the substrate using a laser forming a roughened surface on the surface of the substrate of semiconductive material increasing the surface area of the surface to adhere mold material thereto .

13. (Withdrawn) The semiconductor device according to claim 12, wherein the laser comprises a laser associated with an automolding system.

14. (Withdrawn) The semiconductor device according to claim 12, wherein the laser includes one of an Nd:YAG laser and an excimer laser.

15. (Withdrawn) The semiconductor device according to claim 12, wherein the substrate comprises a ball-grid-array substrate.

16. (Withdrawn) The semiconductor device according to claim 12, further comprising a vision system for detecting the resist.

17. (Withdrawn) The semiconductor device according to claim 16, wherein the vision system comprises: a laser scanning system for detecting changes in a pattern of the substrate.

18. (Canceled)

19. (Canceled)

20. (Canceled)

21. (Canceled)

22. (Canceled)

23. (Canceled)